



HOUSING MATERIAL	:	THERMOPLASTIC POLYESTER UL94V0; GRE
HOUSING CAN WITHSTAND EXPOSURE TO LEAD FREE WAVE SOLDERING TEMPERATURE OF 260-265°C		
WHEN USED WITH PROTECTIVE ADHESIVE OR PROTECTIVE METALLIC DEVICE FOR ANGLE CONNECTORS		
AS IT IS USED IN CLASSICAL LEAD WAVE SOLDERING AT 235-250°C.		
CONTACT & HARPOON MATERIAL	:	COPPER ALLOY
CONTACT ACTIVE ZONE PLATING	:	Au OVER Ni (or) Au+Pd-Ni OVER Ni
CONTACT TERMINATION ZONE PLATING	:	Sn (PURE MATT) OVER Ni
HARPOON PLATING	:	Sn (PURE MATT) OVER Ni

CURRENT RATING AT 20°C	:	1.5 A
CURRENT (I MAX)	:	2 A
TEMPERATURE RANGE	:	-55°C TO +125°C
CONTACT RESISTANCE	:	$\leq 20 \text{ m}\Omega$
INSULATION RESISTANCE	:	$\geq 10^6 \text{ M}\Omega$
TEST VOLTAGE (rms)	:	1000 V

INSERTION FORCE PER CONTACT	:	\leq	0.94 N
EXTRACTION FORCE PER CONTACT	:	\geq	0.15 N
REFERENCE SPECIFICATION	:		DIN 41612 (or) IEC 603-1

SERIES	8609	3	96	7	1	13	7	5	5	STLF
ROWS FITTED WITH CONTACTS										
ROW a b c	3 96									
NO. OF CONTACTS										
TYPE OF INSULATOR										
3 ROW MALE INSULATOR	7									
METHOD OF MOUNTING										
STANDARD MOUNTING - STYLE C	1									
TERMINATION										
ANGLED SPILL	13									
OPTIONS										
NO OPTION	7									
WITH HARPOONS	H									
PERFORMANCE CLASS										
DIN 41612 CLASS 3	4									
DIN 41612 CLASS 2	5									
DIN 41612 CLASS 1	6									
AS PER MIL C 55302 / JSS 50808	8									
PITCH PER ROW										
2.54 mm	5									
SPECIAL CODE: SPECIAL LOADING LEAD FREE VERSION	STLF									

1. THE "LF" PRODUCTS MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
2. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 3.5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6 MM MINIMUM THICK CIRCUIT BOARD.
3. LEAD FREE OR RoHS DIRECTIVE LABELING TO BE PROVIDED AS PER GS-14-920 FOR LEAD FREE VERSION.

[illegible]

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